REV LETTER: E PAGE NO: 1 OF 1 PART NUMBER:

Polymer **PTC Devices**

Surface mount fuses

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LP-MSM075

Features

- Small size of 1812
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA、TUV 💦 🌆 🏧



Product Dimensions (mm)

Dort number	Α	В	С	D	E	
Part number —	Max.	Max.	Max.	Max.	Min.	
LP-MSM075	4.73	3.41	0.61	0.60	0.30	
→ D E			Part Marking S	ystem		
Markin			W	- Product family		
199						

Electrical Characteristics

Dent number	Ι _Η	Ι _Τ	V _{max}	I _{max}	T _{trip}	0	Pd _{typ}	R _{min}	R _{1max}
Part number	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-MSM075	0.75	1.50	13.2	40	8.0	0.20	1.0	0.10	0.48

I_H=Hold current: maximum current at which the device will not trip at 25 still air.

I_T=Trip current: minimum current at which the device will always trip at 25 still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

Imax=Maximum fault current device can withstand without damage at rated voltage.

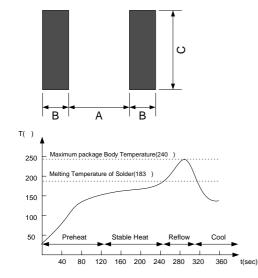
T_{trip}=Maximum time to trip(s) at assigned current.

Pdtvp=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25 prior to tripping.

R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number –	Α	В	С
	(mm)	(mm)	(mm)
LP-MSM075	3.45	1.78	3.15

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.